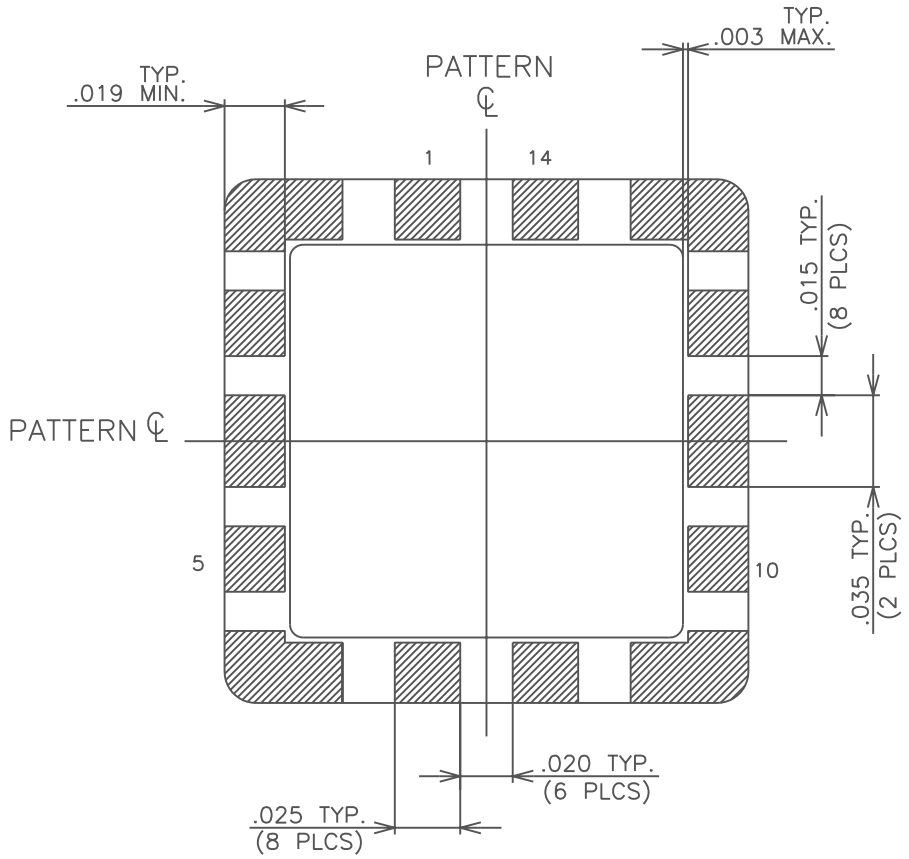


NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.15 OHM MAX.
6. LEAD WIDTH AND THICKNESS NOT CONTROLLED WITHIN .015 FROM CERAMIC.

MODIFICATION △ REDRAWN : CONVERTED CAD DATA. CHANGED					NAME 14 LEAD FLAT PACKAGE		TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION		FB014U131-1 S=0 D=0	
					SCALE 8/1		MATERIAL AS INDICATED		DRAWN S.S. CHECKED A.F. APPROVED S.A. DATE MAR.02.'88	
DATE JUL.31.'00 DRAWN H.K. CHECKED H.TA/S.NI APPROVED H.SA					KYOCERA		KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-F88131-A SHEET 1/2	





BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						14 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	S.S	A.F	S.A	MAR.02.'88
						SCALE 20 / 1					
						MATERIAL					
							THIRD ANGLE PROJECTION				
△	REDRAWN : CONVERTED CAD DATA.	JUL.31.'00	H.K	H.TA/S.NI	H.SA		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET 2 / 2
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-F88131-A			



